Claims

[Claim 1]

A polycrystalline silicon lump packaging body in which a resin bag is filled with polycrystalline silicon lumps having a surface metal concentration of 100 pptw or less, wherein

a nitrate ion amount present inside the packaging body is 5 μg/L or less with respect to a filling void of the polycrystalline silicon lumps formed when the packaging body is left at 25°C under 1 atm.

[Claim 2]

The polycrystalline silicon lump packaging body according to claim 1, wherein

a fluorine ion amount present inside the packaging body is 30 μg/L or less with respect to the filling void of the polycrystalline silicon lumps formed when the packaging body is left at 25°C under 1 atm.

[Claim 3]

The polycrystalline silicon lump packaging body according to claim 1, wherein

the resin bag is filled with polycrystalline silicon lumps having a surface metal concentration of 100 pptw or less and a surface nitrate ion amount of 1.0×10^{-5} μg/mm^2 or less.

[Claim 4]

The polycrystalline silicon lump packaging body according to claim 3, wherein

a fluorine ion amount present on a surface of the polycrystalline silicon lumps is 6.0×10^{-5} μg/mm^2 or less.

[Claim 5]

The polycrystalline silicon lump packaging body according to any one of claims 1 to 4, wherein

a filling void rate of the resin bag filled with the polycrystalline silicon lumps is

40% to 70%.

[Claim 6]

A polycrystalline silicon lump having a surface metal concentration of 100 pptw or less and a surface nitrate ion amount of 1.0×10^{-5} μg/mm^2 or less.

[Claim 7]

The polycrystalline silicon lump according to claim 6, further having a surface fluorine ion amount of 6.0×10^{-5} μg/mm^2 or less.

[Claim 8]

A method of producing the polycrystalline silicon lump according to claim 6, comprising:

drying, at a heating temperature of 120°C to 150°C for 10 minutes to 120 minutes in a cage made of a resin, polycrystalline silicon lumps cleaned body acid-cleaned with an aqueous solution of nitrohydrofluoric acid.

[Claim 9]

A method of producing the polycrystalline silicon lump packaging body according to claim 1, comprising:

drying, at a heating temperature of 120°C to 150°C for 10 minutes to 120 minutes in a cage made of a resin, polycrystalline silicon lumps cleaned body acid-cleaned with an aqueous solution of nitrohydrofluoric acid, and

packing the polycrystalline silicon lumps in the resin bag, filling the resin bag at a filling amount such that the nitrate ion amount present inside the packaging body is 5 μg/L or less with respect to the filling void of the polycrystalline silicon lump formed when the packaging body is left at 25°C under 1 atm.